EL9200, EL9201, EL9202



Data Sheet

April 7, 2005

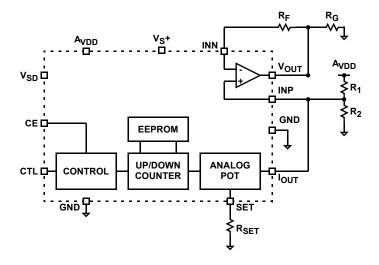
FN7438.0

Programmable V_{COM}

The EL9200, EL9201, and EL9202 represent programmable V_{COM} amplifiers for use in TFT-LCD displays. Featuring 1, 2, and 4 channels of V_{COM} amplification, respectively, each device features just a single programmable current source for adding offset to one V_{COM} output. This current source is programmable using a single wire interface to one of 128 levels. The value is stored on an internal EEPROM memory.

The EL9200 is available in the 12-pin DFN package and the EL9201 and EL9202 are available in 24-pin QFN packages. All are specified for operation over the -40°C to +85°C temperature range.

Typical Block Diagram



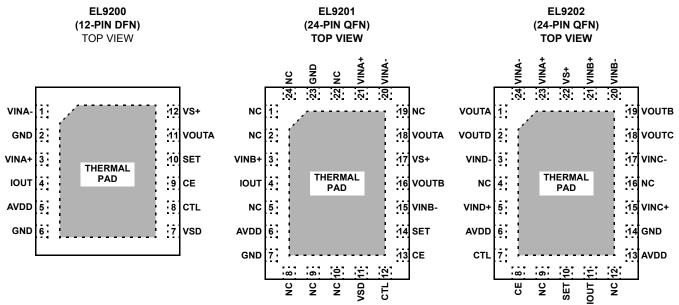
Features

- 128 step adjustable sink current
- EEPROM memory
- · 2-pin adjustment and disable
- · Single, dual or quad amplifiers
 - 44MHz bandwidth
 - 80V/µs slew rate
 - 60mA continuous output
 - 180mA peak output
- Up to 18V operation
- 2.6V to 3.6V logic control
- · Pb-free available (RoHS compliant)

Applications

- TFT-LCD V_{COM} supplies for
 - LCD-TVs
- LCD monitors





Ordering Information

PART NUMBER	PACKAGE	TAPE & REEL	PKG. DWG. #	PART NUMBER	PACKAGE	TAPE & REEL	PKG. DWG. #
EL9200IL	12-Pin DFN	-	MDP0047	EL9201ILZ (See Note)	24-Pin QFN (Pb-Free)	-	MDP0046
EL9200IL-T7	12-Pin DFN	7"	MDP0047	EL9201ILZ-T7 (See Note)	24-Pin QFN (Pb-Free)	7"	MDP0046
EL9200IL-T13	12-Pin DFN	13"	MDP0047	EL9201ILZ-T13 (See Note)	24-Pin QFN (Pb-Free)	13"	MDP0046
EL9200ILZ (See Note)	12-Pin DFN (Pb-Free)	-	MDP0047	EL9202IL	24-Pin QFN	-	MDP0046
EL9200ILZ-T7 (See Note)	12-Pin DFN (Pb-Free)	7"	MDP0047	EL9202IL-T7	24-Pin QFN	7"	MDP0046
EL9200ILZ-T13 (See Note)	12-Pin DFN (Pb-Free)	13"	MDP0047	EL9202IL-T13	24-Pin QFN	13"	MDP0046
EL9201IL	24-Pin QFN	-	MDP0046	EL9202ILZ (See Note)	24-Pin QFN (Pb-Free)	-	MDP0046
EL9201IL-T7	24-Pin QFN	7"	MDP0046	EL9202ILZ-T7 (See Note)	24-Pin QFN (Pb-Free)	7"	MDP0046
EL9201IL-T13	24-Pin QFN	13"	MDP0046	EL9202ILZ-T13 (See Note)	24-Pin QFN (Pb-Free)	13"	MDP0046

NOTE: Intersil Pb-free products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

2

Absolute Maximum Ratings (T_A = 25°C)

$V_S{\mbox{+}}$ Supply Voltage between $V_S{\mbox{+}}$ and GND $\ldots\ldots\ldots.18V$
Supply Voltage between V _{SD} and GND4V
Maximum Continuous Output Current
Input Voltages to GND
SET, CE0.3V to +4V
CTL0.3V to +16V
Output Voltages to GND
OUT0.3V to +20V

 AVDD
 -0.3V to +20V

 ESD Rating - HBM for Device
 2kV

 Ambient Operating Temperature
 -40°C to +85°C

 Maximum Die Temperature
 +150°C

 Storage Temperature
 -65°C to +150°C

 Maximum Lead Temperature (Soldering 10s)
 +300°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typical values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: $T_J = T_C = T_A$

Electrical Specifications $V_{SD} = 3V$, $V_{S} + = 15V$, $A_{VDD} = 15V$, $R_{SET} = 24.9k\Omega$, and $T_A = 25^{\circ}C$ unless otherwise specified

PARAMETER	DESCRIPTION	CONDITION	MIN	TYP	MAX	UNIT
V _{S+}	Supply Voltage		4.5		16.5	V
I _{S+}	Quiescent Current	EL9200		3.8	4.8	mA
		EL9201		7.6	9.6	mA
		EL9202		10.5	16	mA
V _{SD}	Logic Supply Voltage	For programming	3		3.6	V
		For operation	2.6		3.6	V
I _{SD}	Quiescent Logic Current	CE = 3.6V			50	μA
		CE = GND			25	μA
		Program (charge pump current) (Note 1)			23	mA
		Read (Note 1)			3	mA
I _{ADD}	Supply Current	Note 2			25	μA
CTLIH	CTL High Voltage	2.6V < V _{SD} < 3.6V	0.7*V _{SD}		0.8*V _{SD}	V
CTL _{IL}	CTL Low Voltage	2.6V < V _{SD} < 3.6V	0.2*V _{SD}		0.3*V _{SD}	V
CTLIHRPW	CTL High Rejected Pulse Width		20			μs
CTLILRPW	CTL Low Rejected Pulse Width		20			μs
CTLIHMPW	CTL High Minimum Pulse Width		200			μs
CTLILMPW	CTL Low Minimum Pulse Width				200	μs
CTL _{MTC}	CTL Minimum Time Between Counts			10		μs
ICTL	CTL Input Current	CTL = GND			10	μA
		CTL = V _{SD}			10	μA
CTL _{CAP}	CTL Input Capacitance			10		pF
CEIL	CE Input Low Voltage	2.6V < V _{SD} < 3.6V			0.4	V
CEIH	CE Input High Voltage	2.6V < V _{SD} < 3.6V	1.6			V
CE _{ST}	CE Minimum Start Up Time	(Note 1)	1			ms
CTL _{PROM}	CTL EEPROM Program Voltage	2.6V < V _{SD} < 3.6V (Note 2)	4.9		15.75	V
CTL _{PT}	CTL EEPROM Programming Signal Time	> 4.9V	200			μs
PT	Programming Time			100		ms
EE _{WC}	EE Write Cycles	Guaranteed by design	1000			cycles
SETDN	SET Differential Nonlinearity	Monotonic over-temperature		±1		LSB

PARAMETER	DESCRIPTION	CONDITION	MIN	ТҮР	MAX	UNIT
SET _{ZSE}	SET Zero-Scale Error	Note 3			±2	LSB
SET _{FSE}	SET Full-Scale Error	Note 3			±8	LSB
I _{SET}	SET Current	Through R _{SET} (Note 1)			120	μA
SET _{ER}	SET External Resistance	To GND, A _{VDD} = 20V (Note 1)	10		200	kΩ
		To GND, A _{VDD} = 4.5V (Note 1)	2.25		45	kΩ
A _{VDD} to SET	A _{VDD} to SET Voltage Attenuation			1:20		V/V
OUT _{ST}	OUT Settling Time	To ± 0.5 LSB error band (Note 1)		20		μs
V _{OUT}	OUT Voltage Range	(Note 1)	V _{SET} + 0.5V		13	V
OUT _{VD}	OUT Voltage Drift	(Note 1)			10	mV
AMPLIFIER CH	ARACTERISTICS	-		<u> </u>	<u> </u>	1
INPUT CHARA	CTERISTICS					
V _{OS}	Input Offset Voltage	V _{CM} = 0V		3	15	mV
TCV _{OS}	Average Offset Voltage Drift (Note 1)			7		μV/°C
I _B	Input Bias Current	V _{CM} = 0V		2	60	nA
R _{IN}	Input Impedance			1		GΩ
C _{IN}	Input Capacitance			2		pF
CMRR	Common-Mode Rejection Ratio	For V _{IN} from -5.5V to +5.5V	50	70		dB
A _{VOL}	Open-Loop Gain	$-4.5V \le V_{OUT} \le +4.5V$	60	70		dB
OUTPUT CHAF	RACTERISTICS		·			
V _{OL}	Output Swing Low	$R_L = 1.5 k\Omega$ to 0		0.09	0.15	V
V _{OH}	Output Swing High		14.85	14.9		V
I _{SC}	Short-Circuit Current		±150	±180		mA
I _{OUT}	Output Current			±65		mA
POWER SUPP	LY PERFORMANCE					
PSRR	Power Supply Rejection Ratio	$\rm V_{S^+}$ is moved from 4.5V to 15.5V	55	80		dB
DYNAMIC PER	FORMANCE					
SR	Slew Rate (Note 4)	-4.0V \leq V_{OUT} \leq 4.0V, 20% to 80%	60	80		V/µs
t _S	Settling to +0.1% (A_V = +1)	$(A_V = +1), V_{OUT} = 2V \text{ step}$		80		ns
BW	-3dB Bandwidth			44		MHz
GBWP	Gain-Bandwidth Product			32		MHz
PM	Phase Margin			50		٥
CS	Channel Separation	f = 5MHz (EL9201 & EL9202 only)		110		dB
d _G	Differential Gain (Note 5)	$R_F = R_G = 1k\Omega$ and $V_{OUT} = 1.4V$		0.17		%
dP	Differential Phase (Note 5)	$R_F = R_G = 1k\Omega$ and $V_{OUT} = 1.4V$		0.24		٥

Electrical Specifications $V_{SD} = 3V$, $V_{S} + = 15V$, $A_{VDD} = 15V$, $R_{SET} = 24.9k\Omega$, and $T_A = 25^{\circ}C$ unless otherwise specified

NOTES:

1. Simulated and determined via design and not directly tested

4

2. Tested at A_{VDD} = 20V

3. Wafer sort only

4. NTSC signal generator used

Pin Descriptions

PIN	IN/OUT	DESCRIPTION	EQUIVALENT CIRCUIT
VINX-	Input	Amplifier X inverting input, where: X = A for EL9200 X = A, B for EL9201 X = A, B, C, D for EL9202	VS+
VINX+	Input	Amplifier X non-inverting input, where: X = A for EL9200 X = A, B for EL9201 X = A, B, C, D for EL9202	Reference Circuit 1
VS+	Supply	Op amp supply; bypass to GND with 0.1µF capacitor	
VOUTX	Output	Amplifier X output, where: X = A for EL9200 X = A, B for EL9201 X = A, B, C, D for EL9202	VS+ ····
NC	-	No connect; not internally connected	
GND	Supply	Ground connection	
IOUT	Output	Adjustable sink current output pin; the current sinks into the OUT pin is equal to the DAC setting times the maximum adjustable sink current divided by 128; see SET pin function description for the maxim adjustable sink current setting	
SET	Output	Maximum sink current adjustment point; connect a resistor from SET to GND to set the maximum adjustable sink current of the OUT pin; the maximum adjustable sink current is equal to $(A_{VDD}/20)$ divided by R_{SET}	
CE	Input	Counter enable pin; connect CE to V_{DD} to enable counting of the internal counter; connect CE to GND to inhibit counting	
CTL	Input	Internal counter up/down control and internal EEPROM programming control input; if CE is high, a mid-to-low transition increments the 7-bit counter, raising the DAC setting, increasing the OUT sink current, and lowering the divider voltage at OUT; a mid-to-high transition decrements the 7-bit counter, lowering the DAC setting, decreasing the OUT sink current, and increasing the divider voltage at OUT; applying 4.9V and above with appropriately arranged timing will overwrite EEPROM with the contents in the 7-bit counter; see EEPROM Programming section for details	
AVDD	Supply	analog voltage supply; bypass to GND with 0.1µF capacitor	
VSD	Supply	System power supply input; bypass to GND with 0.1µF capacitor	

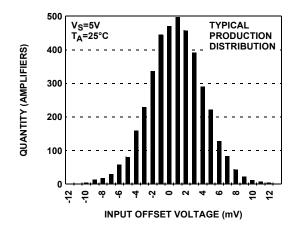


FIGURE 1. INPUT OFFSET VOLTAGE DISTRIBUTION

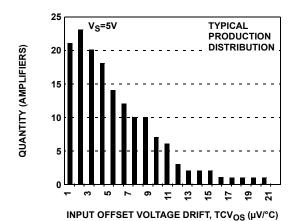


FIGURE 3. INPUT OFFSET VOLTAGE DRIFT

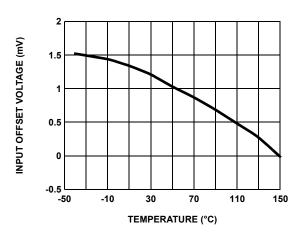


FIGURE 5. INPUT OFFSET VOLTAGE vs TEMPERATURE

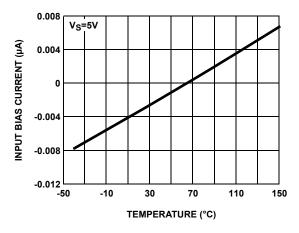
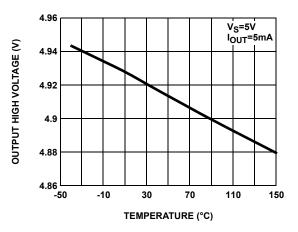
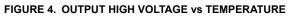


FIGURE 2. INPUT BIAS CURRENT vs TEMPERATURE





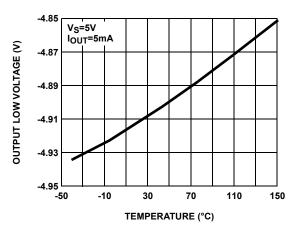


FIGURE 6. OUTPUT LOW VOLTAGE vs TEMPERATURE

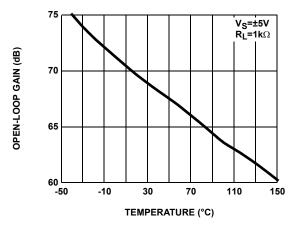


FIGURE 7. OPEN-LOOP GAIN vs TEMPERATURE

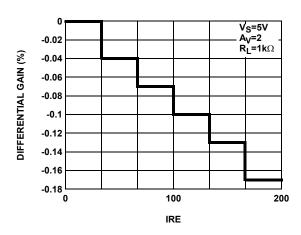


FIGURE 9. DIFFERENTIAL GAIN

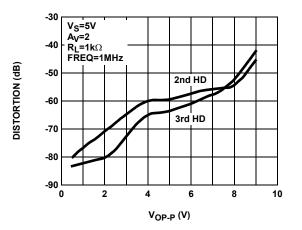
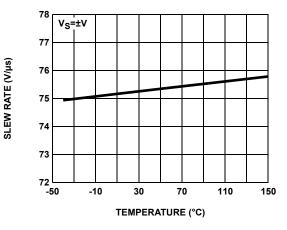


FIGURE 11. HARMONIC DISTORTION vs VOP-P





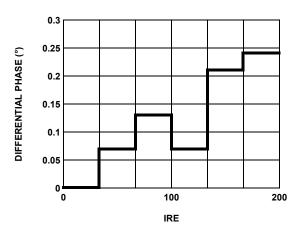


FIGURE 10. DIFFERENTIAL PHASE

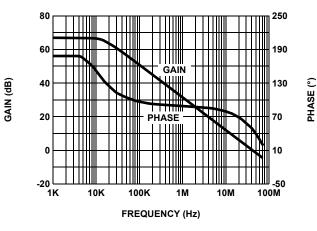


FIGURE 12. OPEN LOOP GAIN AND PHASE

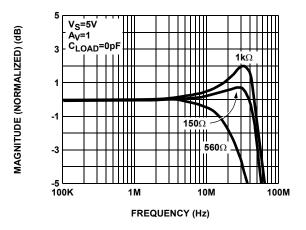


FIGURE 13. FREQUENCY RESPONSE FOR VARIOUS RL

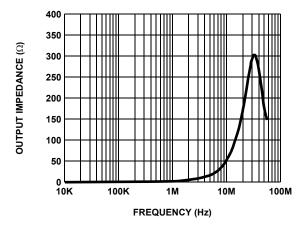


FIGURE 15. CLOSED LOOP OUTPUT IMPEDANCE

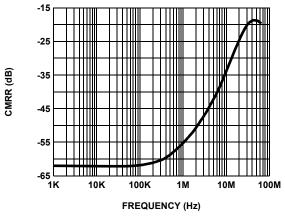


FIGURE 17. CMRR

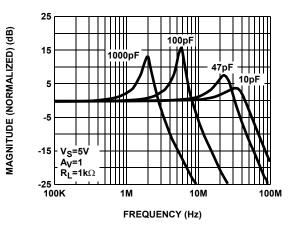


FIGURE 14. FREQUENCY RESPONSE FOR VARIOUS CL

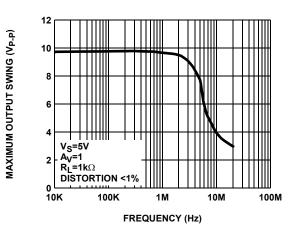


FIGURE 16. MAXIMUM OUTPUT SWING vs FREQUENCY

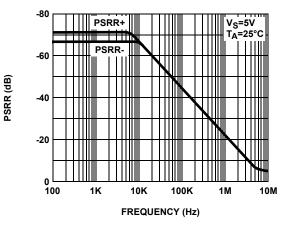


FIGURE 18. PSRR

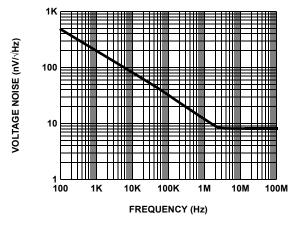
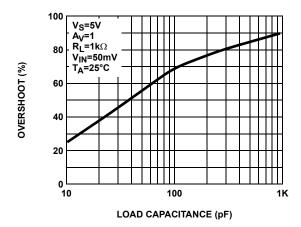
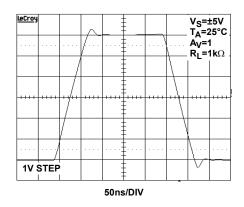


FIGURE 19. INPUT VOLTAGE NOISE SPECTRAL DENSITY









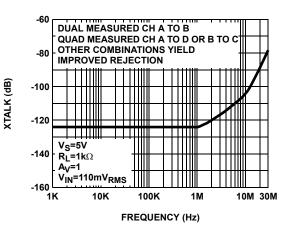


FIGURE 20. CHANNEL SEPARATION

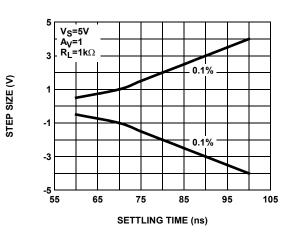
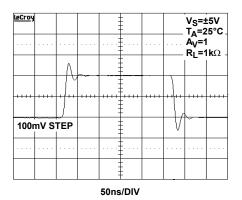


FIGURE 22. SETTLING TIME vs STEP SIZE





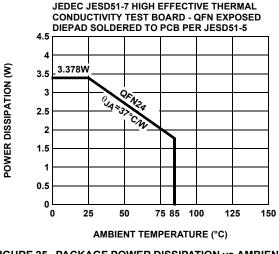


FIGURE 25. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

Application Information

This device provides the ability to reduce the flicker of an LCD panel by adjustment of the V_{COM} voltage during production test and alignment. A 128-step resolution is provided under digital control which adjusts the sink current of the output. The output is connected to an external voltage divider, so that the device will have the capability to reduce the voltage on the output by increasing the output sink current.

The adjustment of the output and the programming of the non-volatile memory are provided on one pin while the counter enable (CE) is provided on a separate pin. The output is adjusted via the CTL pin either by counting up with a mid to low transition or by counting down with a mid to high transition. Once the minimum or maximum value is reached on the 128 steps, the device will not overflow or underflow beyond that minimum or maximum value. An increment of the counter will increase the output sink current which will lower the voltage on the external voltage divider. A decrement of the counter will raise the voltage on the external voltage divider.

Once the desired output level is obtained, the part can store it's setting using the non-volatile memory in the device. See the non-volatile programming section for detailed information.

NOTE: Once the desired output level is stored in the EEPROM, the CE pin must go low to preserve the stored value.

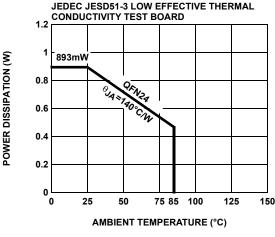


FIGURE 26. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

Adjustable Sink Current Output

The device provides an output sink current which lowers the voltage on the external voltage divider. The equations that control the output are given below:

$$\begin{split} I_{OUT} &= \frac{Setting}{128} \times \frac{A_{VDD}}{20(R_{SET})} \\ V_{OUT} &= \left(\frac{R_2}{R_1 + R_2}\right) V_{AVDD} \left(1 - \frac{Setting}{128} \times \frac{R_1}{20(R_{SET})}\right) \end{split}$$

NOTE: Where setting is an integer between 1 and 128.

7-Bit Up/Down Counter

The counter sets the level to the digital potentiometer and is connected to the non-volatile memory. When the part is programmed, the counter setting is loaded into the nonvolatile memory. This value will be loaded from the nonvolatile memory into the counter during power-on. The counter will not exceed its maximum level and will hold that value during subsequent increment requests on the CTL pin. The counter will not exceed its minimum level and will hold that value during subsequent decrement requests on the CTL pin.

CTL Pin

CTL should have a noise filter to reduce bouncing or noise on the input that could cause unwanted counting when the CE pin is high. The board should have an additional ESD protection circuit, with a series $1k\Omega$ resistor and a shunt 0.01μ F capacitor connected on the CTL pin.

In order to increment the setting, pulse CTL low for more than 200 μ s. The output sink current increases and lowers the V_{COM} lever by one least-significant bit (LSB). On the other hand, to decrement the setting, pulse CTL high for

more than 200 $\mu s.$ The output sink current will decrease and the V_{COM} level will increase by one LSB.

To avoid unintentional adjustment, the EL9200, EL9201, and EL9202 guarantees to reject CTL pulses shorter than 20µs.

Since the internal comparators come up in an unknown state, the very first CTL pulse is ignored to avoid the possibility of a false pulse.

See Figure 27 for the timing information.

IABLE 1. IRUIH IABLE							
	INPUT			OUTPUT			
CTL	CE	V _{DD}	SET	lcc	MEMORY		
Mid to Hi	Hi	V _{DD}	Decrement	Normal	Х		
Mid to Lo	Hi	V _{DD}	Increment	Normal	Х		
Х	Lo	V _{DD}	No Change	Lower	х		
> 4.9V	Х	V _{DD}	No Change	Increased	Program		
Х	Х	0 to V _{DD}	Read	Increased	Read		

NOTE: CE should be disabled (pulled low) before powering down the device to assure that the glitches and transients will not cause unwanted EEPROM overwriting.

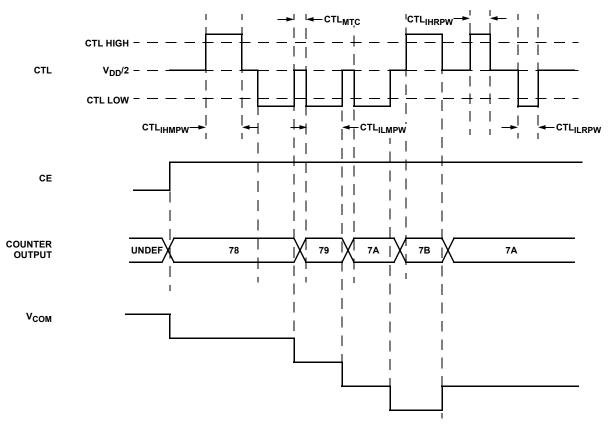


FIGURE 27. V_{COM} ADJUSTMENT

Non-Volatile Memory (EEPROM) Programming

When the CTL pin exceeds 4.9V, the non-volatile programming cycle will be activated. The CTL signal needs to remain above 4.9V for more than 200μ s. The level and timing needed to program the non-volatile memory is given below. It then takes a maximum of 100ms for the programming to be completed inside the device (see P_T specification in Electrical Specification Table).

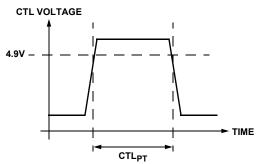


FIGURE 28. EEPROM PROGRAMMING

Amplifiers' Operating Voltage, Input, and Output

The amplifiers are specified with a single nominal supply voltage from 5V to 15V or a split supply with its total range from 5V to 15V. Correct operation is guaranteed for a supply range of 4.5V to 16.5V. Most amplifier specifications are stable over both the full supply range and operating temperatures of -40°C to +85°C. Parameter variations with operating voltage and/or temperature are shown in the typical performance curves.

The input common-mode voltage range of the amplifiers extends 500mV beyond the supply rails. The output swings of the those typically extend to within 100mV of positive and negative supply rails with load currents of 5mA. Decreasing load currents will extend the output voltage range even closer to the supply rails. Figure 27 shows the input and output waveforms for the device in the unity-gain configuration. Operation is from 5V supply with a 1k Ω load connected to GND. The input is a 10V_{P-P} sinusoid. The output voltage is approximately 9.8V_{P-P}.

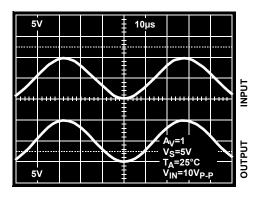


FIGURE 29. OPERATION WITH RAIL-TO-RAIL INPUT AND OUTPUT

Short-Circuit Current Limit

The amplifiers will limit the short circuit current to ± 180 mA if the output is directly shorted to the positive or the negative supply. If an output is shorted indefinitely, the power dissipation could easily increase such that the device may be damaged. Maximum reliability is maintained if the output continuous current never exceeds ± 65 mA. This limit is set by the design of the internal metal interconnects.

Output Phase Reversal

The amplifiers are immune to phase reversal as long as the input voltage is limited from V_{S^-} -0.5V to V_{S^+} +0.5V. Figure 28 shows a photo of the output of the device with the input voltage driven beyond the supply rails. Although the device's output will not change phase, the input's over-voltage should be avoided. If an input voltage exceeds supply voltage by more than 0.6V, electrostatic protection diodes placed in the input stage of the device begin to conduct and over-voltage damage could occur.

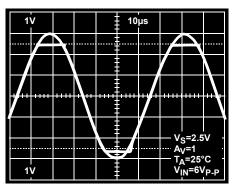


FIGURE 30. OPERATION WITH BEYOND-THE-RAILS INPUT

Unused Amplifiers

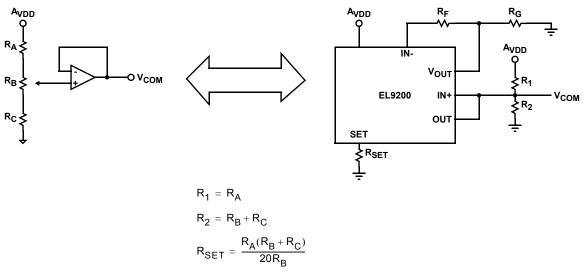
It is recommended that any unused amplifiers in a dual and a quad package be configured as a unity gain follower. The inverting input should be directly connected to the output and the non-inverting input tied to the ground plane.

Power Supply Bypassing and Printed Circuit Board Layout

The amplifiers can provide gain at high frequency. As with any high-frequency device, good printed circuit board layout is necessary for optimum performance. Ground plane construction is highly recommended, lead lengths should be as short as possible and the power supply pins must be well bypassed to reduce the risk of oscillation. For normal operation a 0.1μ F ceramic capacitor should be placed from V_S to pin to GND. A 4.7μ F tantalum capacitor should then be connected in parallel, placed in the region of the amplifier.

Replacing Existing Mechanical Potentiometer Circuits

Figures 29 and 30 show the common adjustment mechanical circuits and equivalent replacement with the EL920X.





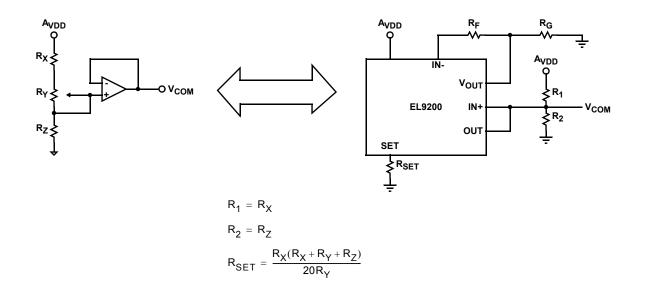
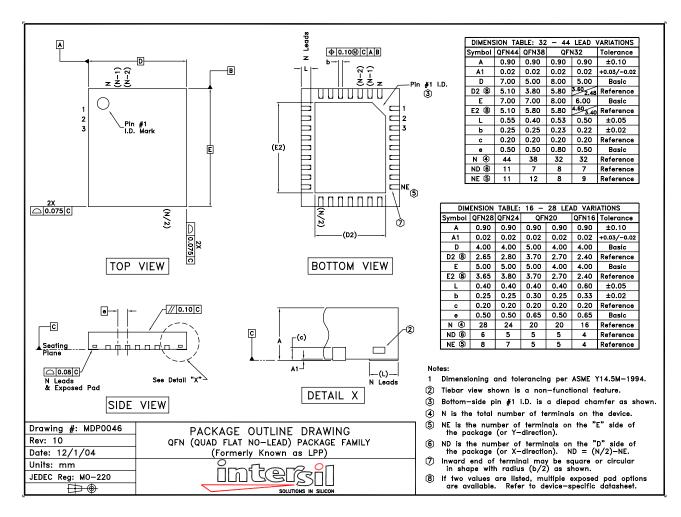


FIGURE 32. EXAMPLE OF THE REPLACEMENT FOR THE MECHANICAL POTENTIOMETER CIRCUIT USING THE EL9200

QFN Package Outline Drawing



NOTE: The package drawing shown here may not be the latest version. To check the latest revision, please refer to the Intersil website at http://www.intersil.com/design/packages/index.asp

All Intersil U.S. products are manufactured, assembled and tested utilizing ISO9000 quality systems. Intersil Corporation's quality certifications can be viewed at www.intersil.com/design/quality

Intersil products are sold by description only. Intersil Corporation reserves the right to make changes in circuit design, software and/or specifications at any time without notice. Accordingly, the reader is cautioned to verify that data sheets are current before placing orders. Information furnished by Intersil is believed to be accurate and reliable. However, no responsibility is assumed by Intersil or its subsidiaries for its use; nor for any infringements of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Intersil or its subsidiaries.

For information regarding Intersil Corporation and its products, see www.intersil.com